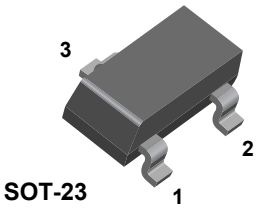
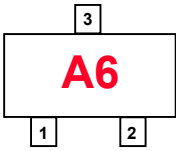
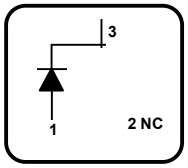
FAIRCHILD
SEMICONDUCTOR TM

BAS16





CONNECTION DIAGRAM



High Conductance Ultra Fast Diode

Sourced from Process 1P. See BAV99 for characteristics.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
W_{IV}	Working Inverse Voltage	75	V
$I_{F(AV)}$	Average Rectified Current	200	mA
I_{FM}	DC Forward Current	600	mA
I_{FRM}	Recurrent Peak Forward Current	700	mA
I_{FSM}	Non-repetitive Peak Forward Surge Current Pulse width = 1.0 second Pulse width = 1.0 microsecond	 1.0 2.0	 A A
T_{stg}	Storage Temperature Range	-50 to +150	°C
T_J	Operating Junction Temperature	150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:
1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Parameter	Max	Units
		BAS16	
P_D	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

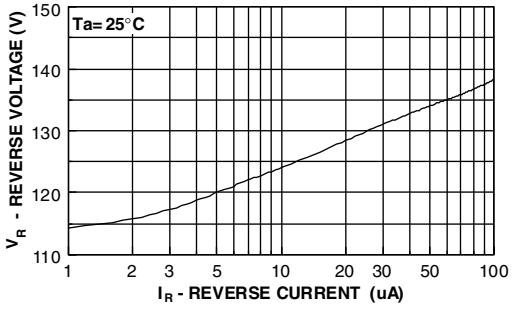
High Conductance Ultra Fast Diode
(continued)

Electrical Characteristics
TA = 25°C unless otherwise noted

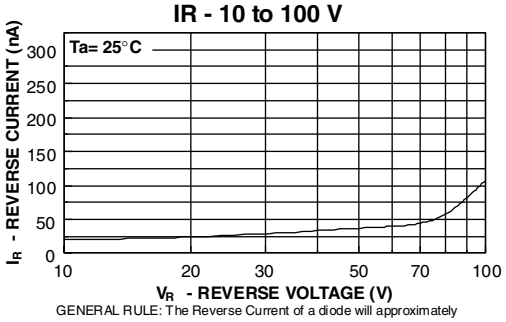
Symbol	Parameter	Test Conditions	Min	Max	Units
V_R	Breakdown Voltage	I_R = 5.0 μA	85		V
I_{RM}	Maximum Instantaneous Reverse Current	V_R = 25 V, T_A = 150°C V_R = 75 V V_R = 75 V, T_A = 150°C		30 1.0 50	μA μA μA
V_{FM}	Maximum Instantaneous Forward Voltage	I_F = 1.0 mA I_F = 10 mA I_F = 50 mA I_F = 150 mA		715 855 1.0 1.25	mV mV V V
C_O	Diode Capacitance	V_R = 0, f = 1.0 MHz		2.0	pF
t_{rr}	Reverse Recovery Time	I_F = 10 mA, V_R = 6.0 V, I_{RR} = 1.0 mA, R_L = 100Ω		6.0	ns

Typical Characteristics

REVERSE VOLTAGE vs REVERSE CURRENT
BV - 1.0 to 100 uA

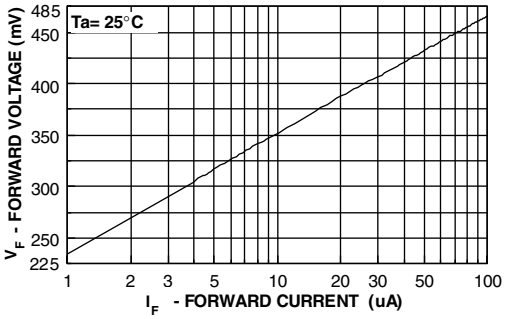


REVERSE CURRENT vs REVERSE VOLTAGE
IR - 10 to 100 V

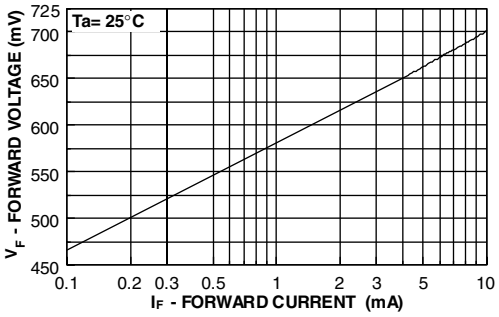


GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature

FORWARD VOLTAGE vs FORWARD CURRENT
VF - 1.0 to 100 uA



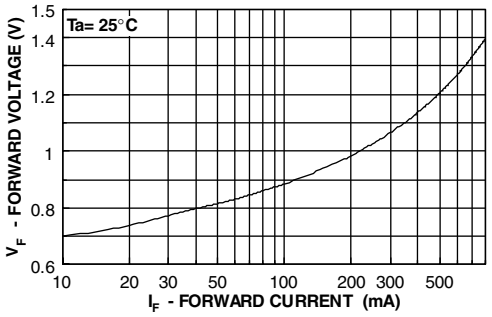
FORWARD VOLTAGE vs FORWARD CURRENT
VF - 0.1 to 10 mA



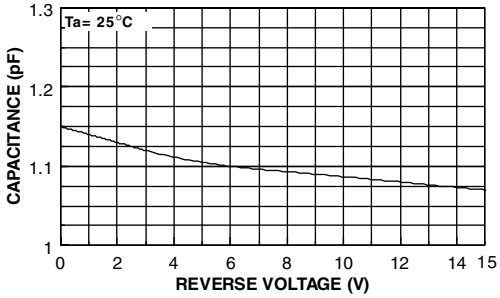
High Conductance Ultra Fast Diode
(continued)

Typical Characteristics (continued)

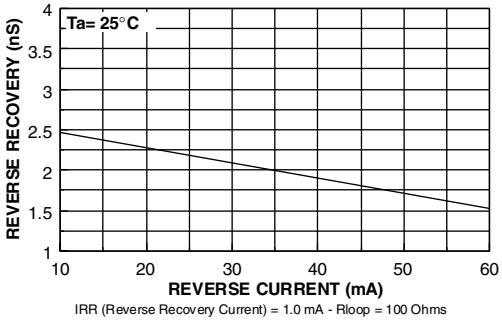
FORWARD VOLTAGE vs FORWARD CURRENT
VF - 10 - 800 mA



CAPACITANCE vs REVERSE VOLTAGE
VR - 0.0 to 15 V

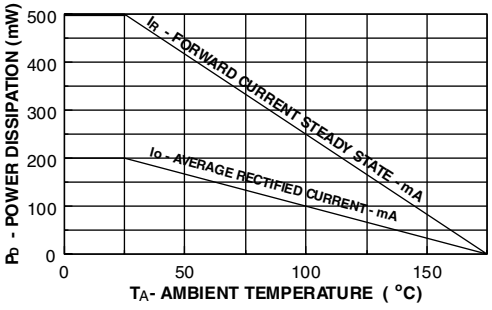


REVERSE RECOVERY TIME vs REVERSE CURRENT
TRR - IR 10 mA vs 60 mA

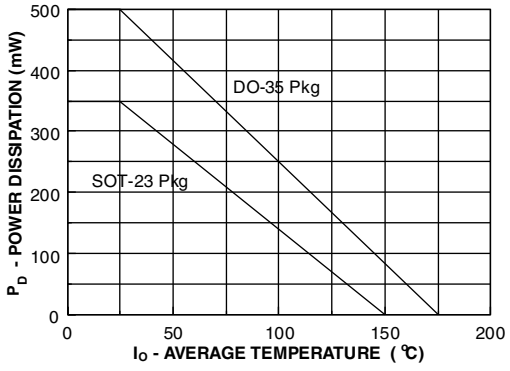


IRR (Reverse Recovery Current) = 1.0 mA - Rloop = 100 Ohms

Average Rectified Current (Io) & Forward Current (I_F) versus Ambient Temperature (T_A)



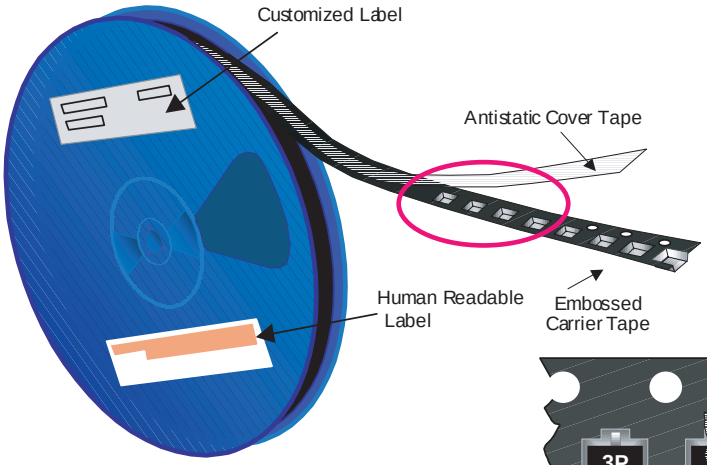
POWER DERATING CURVE



SOT-23 Tape and Reel Data

FAIRCHILD SEMICONDUCTOR™

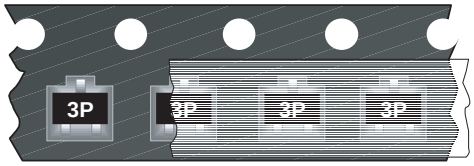
SOT-23 Packaging Configuration: Figure 10



Packaging Description:

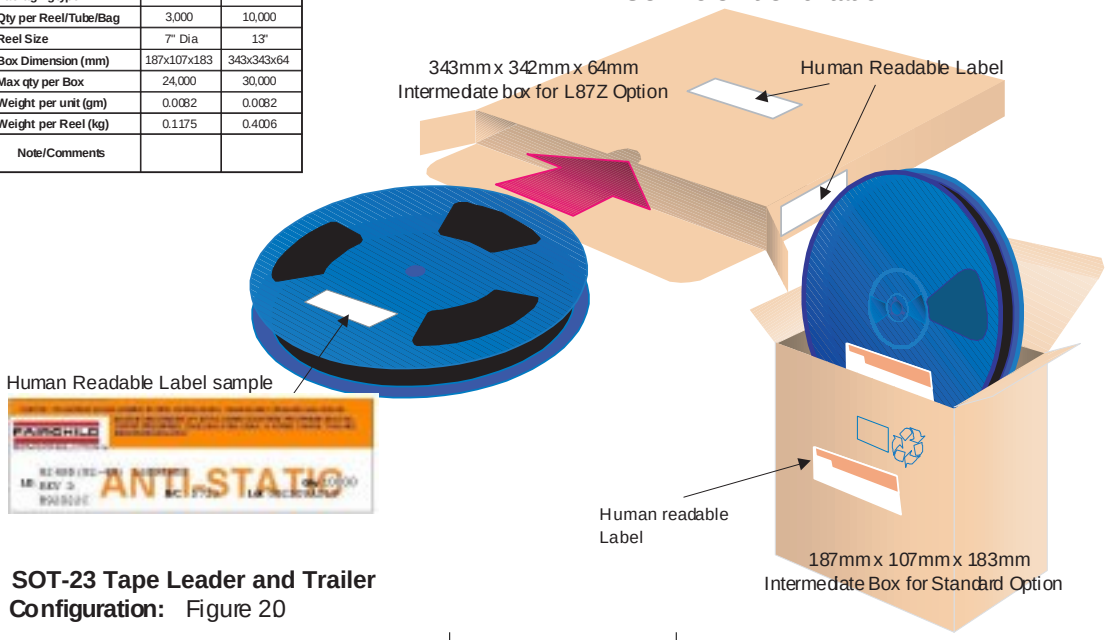
SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually labeled and placed inside a standard intermediate made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains eight reels maximum. And these intermediate boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped.

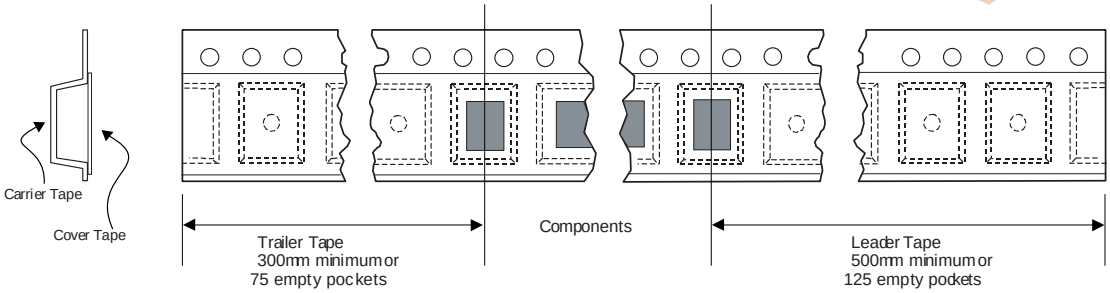


SOT-23 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	187x107x183	343x343x64
Max qty per Box	24,000	30,000
Weight per unit (gm)	0.0082	0.0082
Weight per Reel (kg)	0.1175	0.4006
Note/Comments		

SOT-23 Unit Orientation

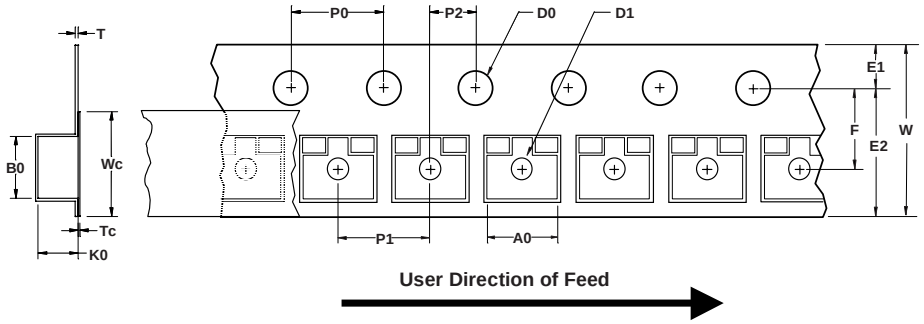


SOT-23 Tape Leader and Trailer Configuration: Figure 20



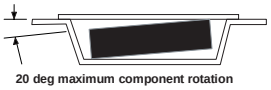
SOT-23 Tape and Reel Data, continued

SOT-23 Embossed Carrier Tape
Configuration: Figure 3.0

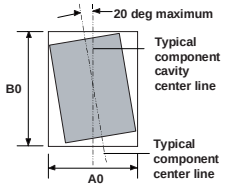


Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

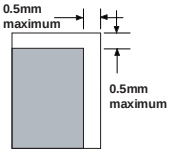
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

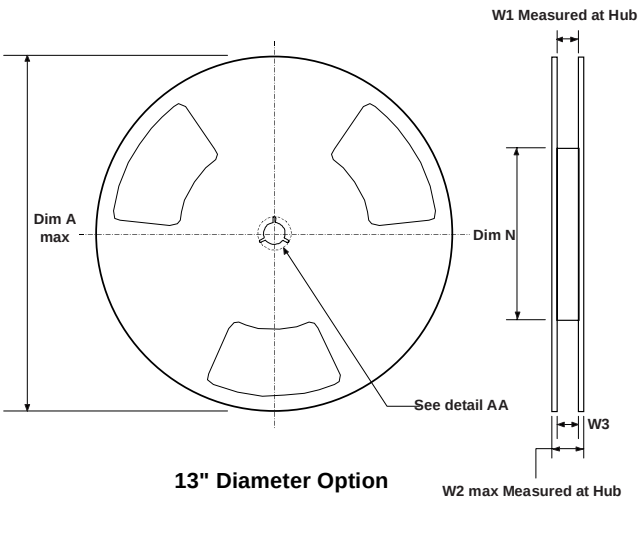


Sketch B (Top View)
Component Rotation

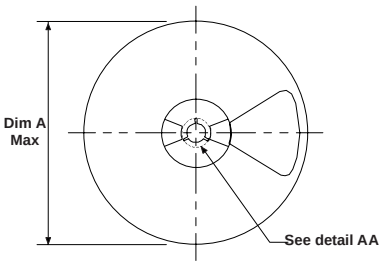


Sketch C (Top View)
Component lateral movement

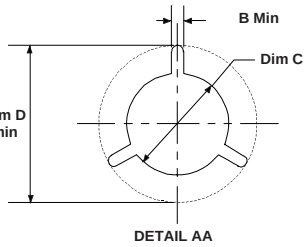
SOT-23 Reel Configuration: Figure 4.0



13" Diameter Option



7" Diameter Option

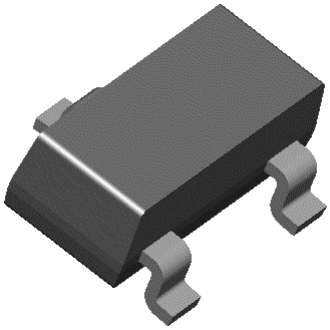


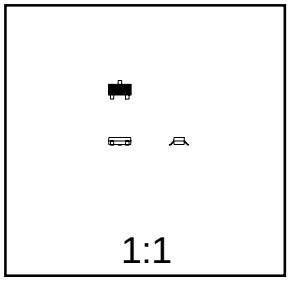
Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9

SOT-23 Package Dimensions

FAIRCHILD SEMICONDUCTOR™

SOT-23 (FS PKG Code 49)

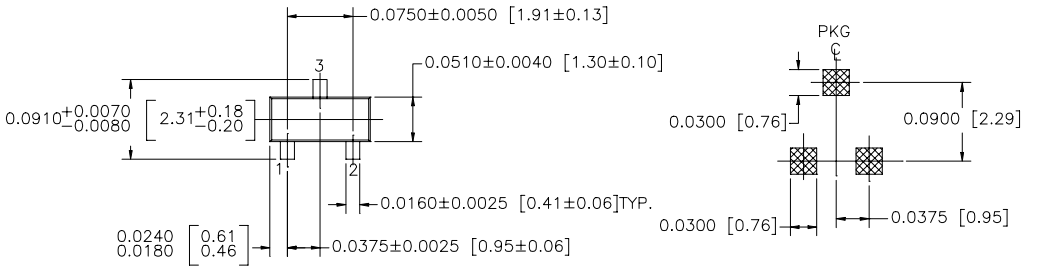


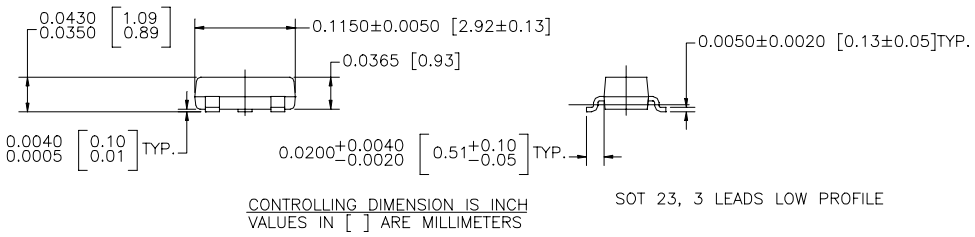


Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.0082





NOTE : UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
2. REFERENCE JEDEC REGISTRATION TO−236, VARIATION AB, ISSUE G, DATED JUL 1993

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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